

# Approval Sheet

Products	Chip Antenna	3D Structure
Supplier CODE	ACS2450JBAUBC	
Model	UBC-100	TUBC9CM
SEC CODE		Top-Side View
Revision	VER.1.0 12/22	
Supplier	PARTRON	Bottom-Side View

MSL	LEAD FREE	BFRs-Free, Halogen-Free	
MSL 1	LEAD-FREE	BFRs/CFRs/PVC-Free	

By designed	By checked	By approved
다	with	Strike
Chang-hun.Mun	Chanik.Jeon	Nam-Sik.Min
12/22	12/22	12/22

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## 1. Revision

Revision No	Originator	Description of changes	Date of changes
Ver 1.0	Chanik.Jeon	Issued	2009.12.22
Ver 1.1	Chanik.Jeon	correct typos 6p 4.3 Test Fixture Condition - Lower and Upper Frequency SRW SPEC is corrected 1.0 ~ 3.0 : 1 (Typ 2.5 :1) → 1.0 ~ 2.5 : 1 (Typ 2.0 : 1)	2009.01.14

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## 2. Summary of Parts & Dimension

#### 2.1 Summary of Parts

This product is the internal dielectric chip antenna of radio communication, forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics.

## 2.2 Dimension of parts

Туре	Only Bulk Ceramic					
	Dielectric Block		Mg₂SiO₄(Magnesium Silicate)			
Material	Electro	ode Paste		Ag		
	L = 1	0.0 ± 0.1				
Size [mm]	W = 2	2.5 ± 0.1		Ag Paste		
	T = 1	l.2 ± 0.1				
Flatness Level	0.04		L			1
MSL LEVEL	MSL	LEVEL 1	TUBC9CM			
ESD LEVEL		nan 15 KV CLASS 3B)	Dielectric Block Top-Side View Bottom-Side View			
Version	Revis	sion 1.0				ide View
Electrical	Characteristics	VSWR(CTF)	Cycle of management	Q`ty	СРК	Reference
	Characteristics (CTF) 2730MHz 1.0 ~ 2.5:1 2815MHz 1.0 ~ 2.5:1		all inspection	all	6.50	4,6,15 Page
(3.4.4)			all inspection	all	10.59	4,6,15 Page

# 3. Critical to Quality( )

- The following list is specified as the emphasis management list and managed.

CTQ Item	SPEC	Cycle of management	measurement System
Plasticity Temperature	1350 <u>+</u> 15 ℃	three times a day	Temperature Sensor
Dry Temperature	200 <u>+</u> 15 ℃	three times a day	Temperature Sensor
Hot Belt Conveyor Temperature	900 <u>+</u> 25℃	three times a day	Temperature Sensor

CTF Item 📀	Specification Reason			
Single Element Measurement SWR	This item is an important parameter that fixs an electrical characteristic			
Single Element Measurement Dimension	Dimension Degree of precision is an important item of characteristic of chip antenna			

- require attention for the following list.

ITEM	Content
Keeping	Sealing tightly when keeping for a long time.
Action	Maybe characteristics changes when changing any design.

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## 4. Electrical Characteristics

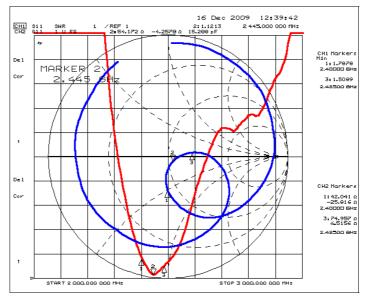
#### 4.1 Set Condition

	ITE	M	SPEC	
Frequency Range [MHz]			2400 ~ 2485	
	SWR	[Max]		3.0 : 1 (Typ 2.5 : 1)
	Input Impe	dance $[\Omega]$		50 Ohm
	Polariz	zation		Linear
	Total Gair	n ( Peak / /	Avg ) [dBi]	0.39 / -3.71
		Thete	Peak	-0.96
	Azimuth  Elevation 1	Theta	Average	-4.03
		Phi	Peak	0.39
			Average	-3.57
		Theta	Peak	0.90
Gain [dBi]		rneta	Average	-2.51
		DI.	Peak	0.25
		Phi	Average	-5.07
		Thete	Peak	-1.38
	Elevation 2	Theta	Average	-6.07
			Peak	2.16
		Phi	Average	-2.22

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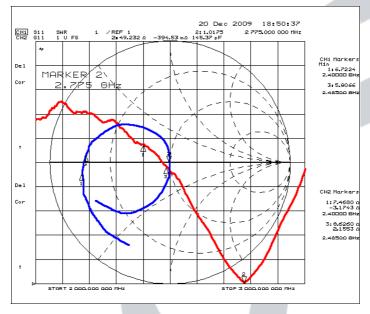
#### 4.2 S11 Graph of Set Condition



#### 4.3 Test Fixture Condition

ITEM	SPEC
Frequency Range [MHz]	2730 ~ 2815
Lower frequency(2730 MHz) SWR [Min~Max]	1.0 ~ 2.5 : 1 (Typ 2.0 : 1)
Upper frequency(2815 MHz) SWR [Min~Max]	1.0 ~ 2.5 : 1 (Typ 2.0 : 1)

## 4.4 S11 Graph of Test Fixture Condition

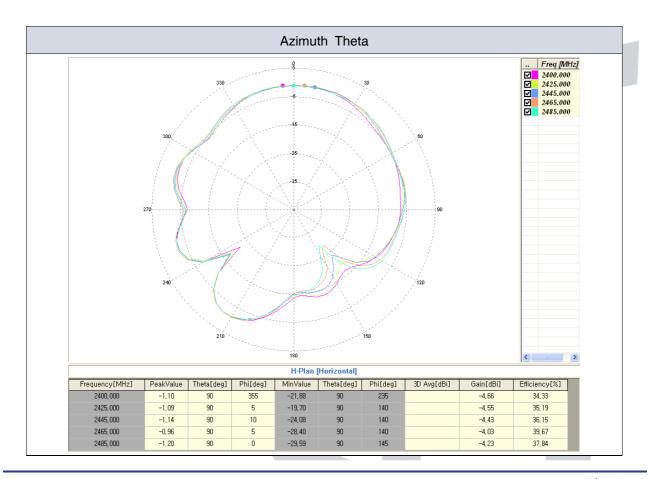


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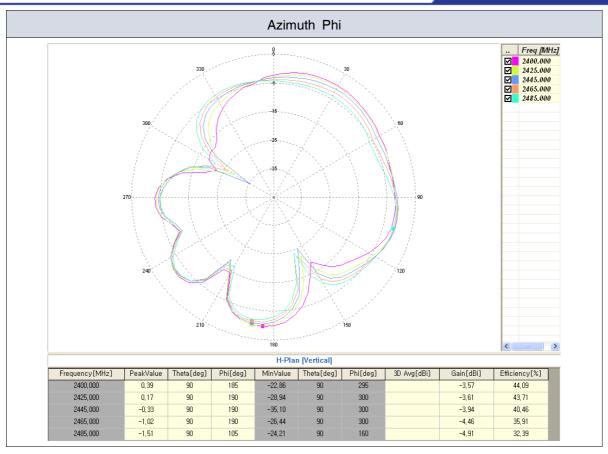
## 4.5 Radiation Pattern

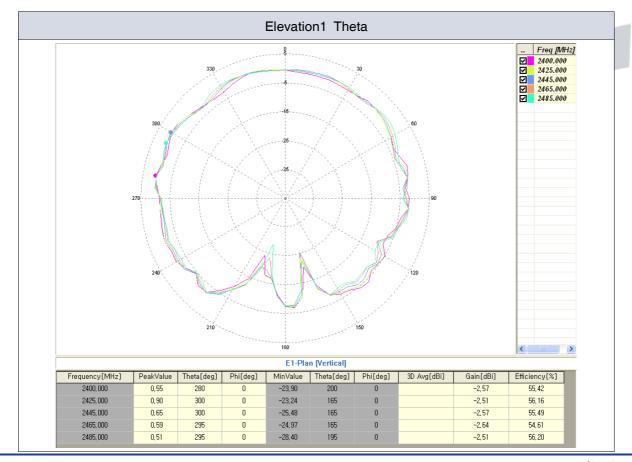
Azimuth Plane	Elevation1 Plane	Elevation2 Plane	
270° 90°	90° 180°	270° ————————————————————————————————————	
Theta	Vertical field of measured plane		
Phi	Horizontal field of measured plane		



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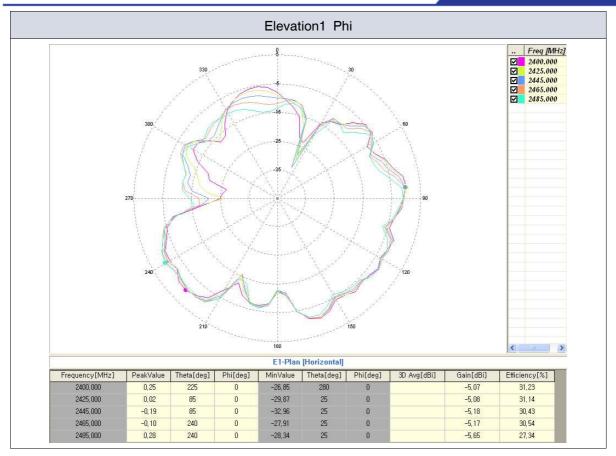


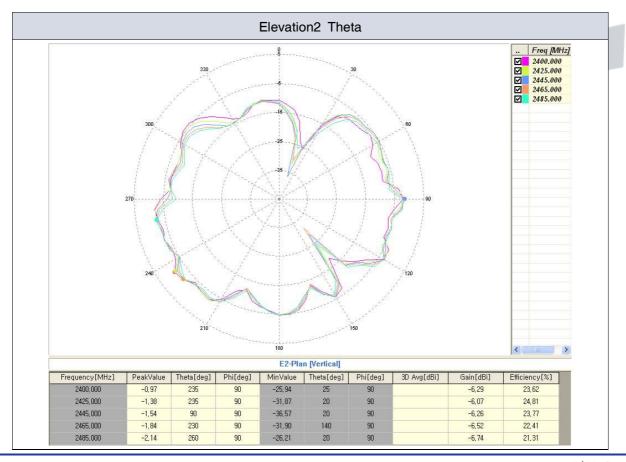




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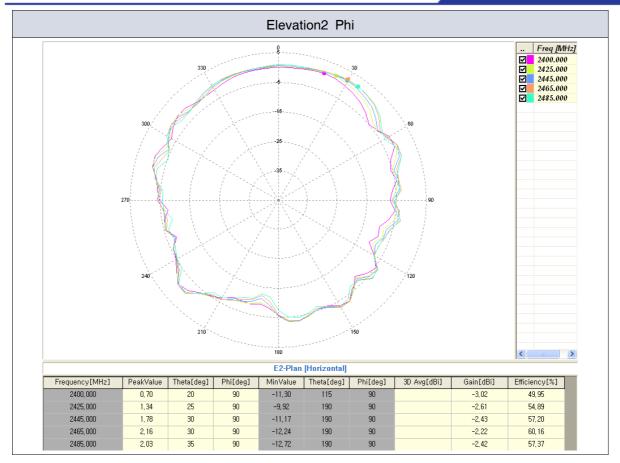






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#### 5. Measurement Process

#### 5.1 SWR / Return Loss

Use Network Analyzer when measuring SWR/Return loss and selecting standard SPL, Use automatic inspection equipment when selecting superior and inferior goods.

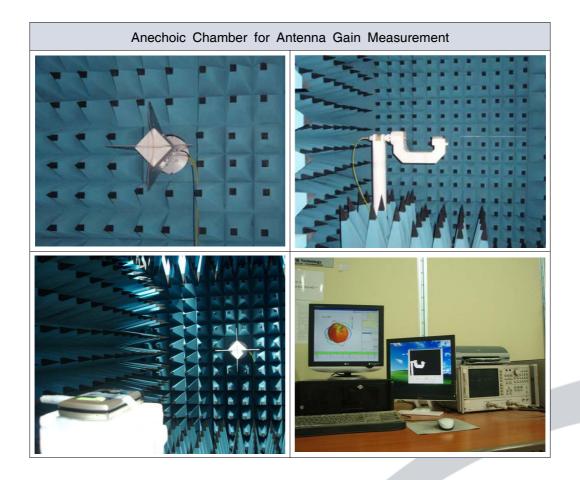
	Set Condition	Test Fixture Condition
Network Analyzer	Agilent HP8753E or Advantest R3765CH	Agilent HP8753E or Advantest R3765CH
Cable	RF cable (300 mm)	RF cable (300 mm)
Test condition		

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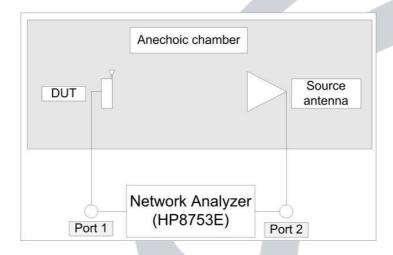


#### 5.2 Gain

Antenna gain is measured in the Anechoic Chamber of this company, using set above of 4.1 list.



#### 5.3 Gain test block diagram

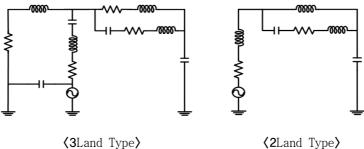


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#### 6. Internal Block Diagram

This product is made of the dielectric block and RF part materialized the characteristics by structural change of Ag pattern on the brick of dielectric block and conditioning value of the structural equivalent circuit.



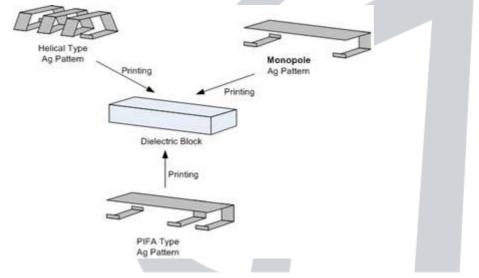
#### 7. Basis Action / Application Note

This product is the internal dielectric chip antenna of radio communication, coverts the electric signal advanced along by transmission line into free space wave.

This product will be mounted wherever you want and the design is revised by mount condition. But require attention to select the mount position, because this product is the radiation part and changed characteristics by boundary condition,



As the following, this product is easy to revise the various types for the boundary condition.



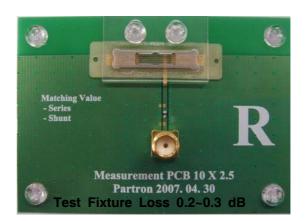
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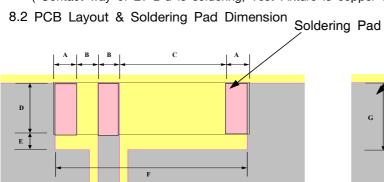
## 8. Measurement Jig SPEC

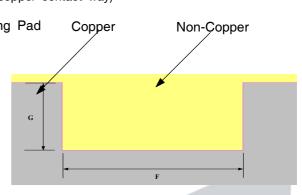
#### 8.1 Test Fixture And Test PCB





※ Ev B'd and Test Fixture Jig is the same ( Contact way of Ev B'd is soldering, Test Fixture is copper contact way)





**Top Layout** 

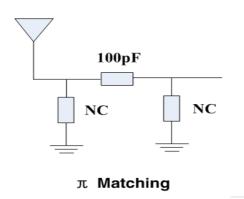
#### **Bottom Pattern**

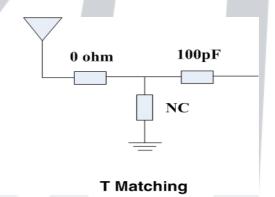
Parameter	Α	В	С	D	Е	F	G
Value[mm]	1.1	1.0	6.0	2.5	1.0	10	3.5

Unit; mm

Unless specified tolerances are ±0.05

#### 8.3 Matching Circuit And Reference Value



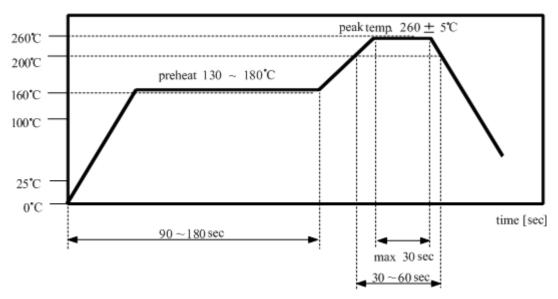


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#### 9. REFLOW PROFILE

#### 9.1 Reflow Soldering

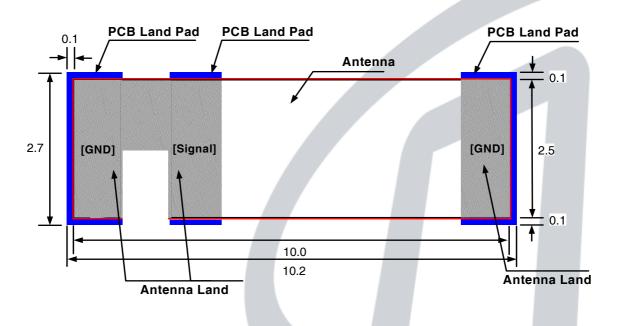


#### 9.2 Manual Soldering

Soldering Temperature : 340  $^{\circ}\text{C} \pm 5\,^{\circ}\text{C}$  , 5sec max per each terminal.

#### 9.3 PCB Pattern Design

As the following, the PCB land pattern lays out 0.1mm outside land pattern of antenna more than indicated antenna land dimension.



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## 10. Primary Inspection List

Item	Frequency [MHz]			Size [mm]		
0	SWR 2	2.5 Max	W 05.04 1 400.04		T 1001	
Standard	2730 MHz	2815 MHz	$W = 2.5\pm0.1$	L = 10.0±0.1	T = 1.2±0.1	
1	1.46	1.55	2.52	10.01	1.22	
2	1.50	1.48	2.53	10.02	1.23	
3	1.51	1.48	2.53	10.03	1.23	
4	1.44	1.50	2.53	10.01	1.23	
5	1.43	1.57	2.52	10.01	1.22	
6	1.56	1.50	2.54	10.01	1.24	
7	1.55	1.50	2.52	10.02	1.22	
8	1.49	1.56	2.53	10.02	1.23	
9	1.53	1.52	2.52	10.02	1.21	
10	1.53	1.51	2.53	10.02	1.23	
11	1.55	1.54	2.53	10.03	1.23	
12	1.52	1.53	2.52	10.03	1.22	
13	1.55	1.50	2.54	10.02	1.24	
14	1.53	1.53	2.52	10.01	1.22	
15	1.60	1.57	2.53	10.01	1.23	
16	1.56	1.53	2.53	10.02	1.21	
17	1.59	1.53	2.52	10.03	1.22	
18	1.56	1.51	2.54	10.03	1.24	
19	1.60	1.47	2.52	10.01	1.22	
20	1.59	1.47	2.52	10.02	1.22	
Min	1.43	1.47	2.52	10.01	1.21	
Max	1.60	1.57	2.54	10.03	1.24	
Х	0.53	0.52	2.52	10.01	1.22	
σ	0.05	0.03	0.01	0.01	0.01	
Cpk	6.50	10.59	3.28	3.38	2.76	
Decision	Ok	Ok	Ok	Ok	Ok	

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## 11. Reliability Condition

#### 11.1 Environment Test

ITEM	TEST CONDITION	LIMIT
PCT	+121±5 ℃, RH=100%, 96 hr	
Low Temperature Action	-40℃± 3℃, 1hr	
Low Temperature Resistance	-40℃± 3℃, 120hr	After test, Must meet the characteristics spec of
Humidity Action	+85± 3℃, RH85%	4.4 list
Humidity Resistance	+85± 3℃, RH85%, 120hr	

## 11.2 Thermal shock test, Reflow test

ITEM	TEST CONDITION	LIMIT
	condition : -40 $^{\circ}\text{C} \pm 3 ^{\circ}\text{C}/1 \text{min} \leftrightarrow +85 ^{\circ}\text{C} \pm 3 ^{\circ}\text{C}/1 \text{min}$	
Thermal shock	Test Cycle: 32 cycle	After test Most west the
	Temperature change time: within 5 min	After test, Must meet the
Reflow	Pre Heating : $200\pm5$ °C, $30$ ~60 sec Peak Heating : $260$ °C±5°C, $30$ sec Max	characteristics spec of 4.4 list

#### 11.3 Mechanical Test

ITEM	TEST CONDITION	LIMIT
Vibration	Freq: 10~500Hz, Acceleration: 10 ×9.8 m/s (G) Sweep time: 15 min, X.Y.Z each 5 times	After test, Must meet the
Drop	18 times free fall Using the drop jig 152cm high Jig: 120g± 20g Plastic Jig Bottom: Concrete or Iron	characteristics spec of 4.4 list

#### 11.4 MSL LEVEL Test

#### 1) JEDEC J-STD-020C Test

	Floor Life		Soak F	Requirements
	Time	Conditions	Time	Conditions
1	Unlimited	= < 30°C / RH 85%	168+5 / -0	= < 85°C / RH 85%

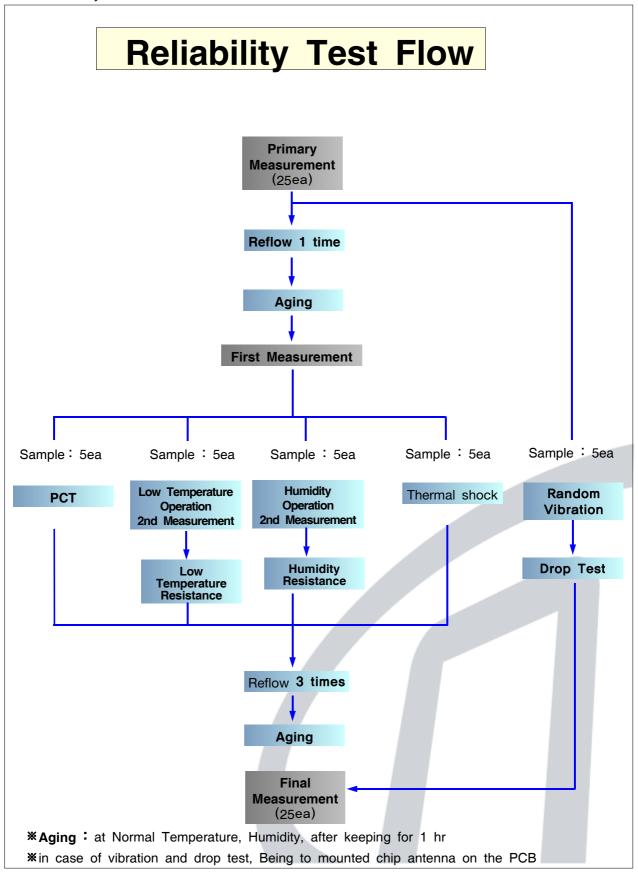
#### 2) Test Condition

ITEM	Conditon	LIMIT
Soak Requirements	After leaving +85± 3℃, RH85% 168hr± 3 times Reflow without aging	2hr After test, Must meet the characteristics spec of 4.4 list

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#### 11.5 Reliability Flow

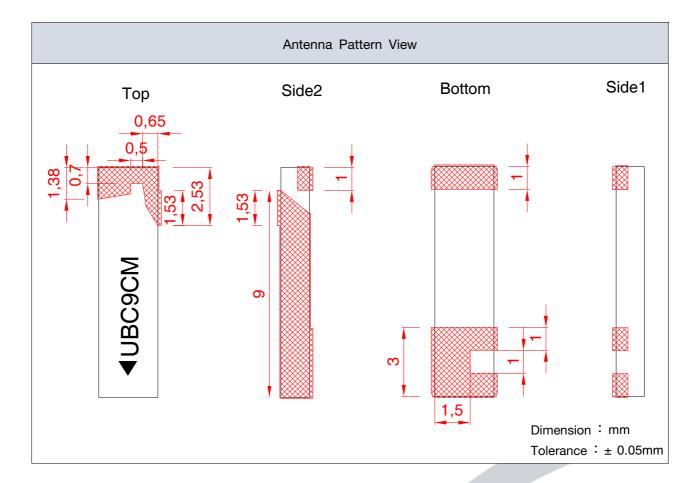


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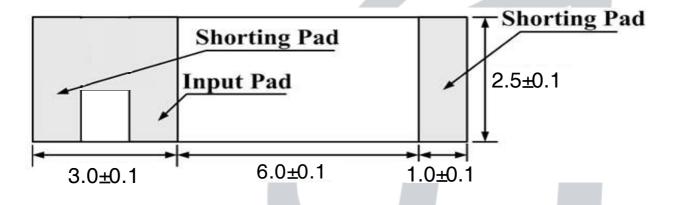


#### 12. Mechanical Characteristics

#### 12.1 Antenna Pattern Dimension



#### 12.2 Pin name



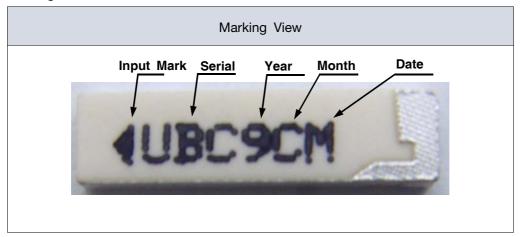
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#### 12.3 Lot number notation

- ① Year : 1 2001, 2 2002 ···· 9 2009 ····
- 2 Month: 1 January, 2 February · · · · A October, B November, C December · · · ·
- ③ Date : 1 1st, 2 2nd · · · · K 20th, L 21th, M 22th · · · ·

#### 12.4 Marking





- 1 Input Signal
- 2 Serial
- ③ Year : 1-2001, 2-2002 ···· 9-2009 ····
- 4 Month: 1 January, 2 February .... A October, B November, C December ....
- ⑤ Date : 1 1st, 2 2nd · · · · K 20th, L 21th, M 22th · · · ·

#### 12.5 Marking type

Ink marking - Using Black Ink

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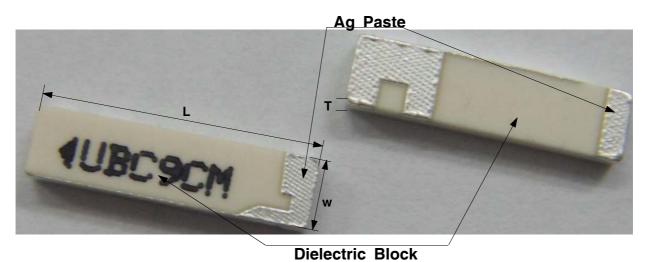


#### 13. Structure and Material

#### 13.1 materialization method

Chip antenna forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

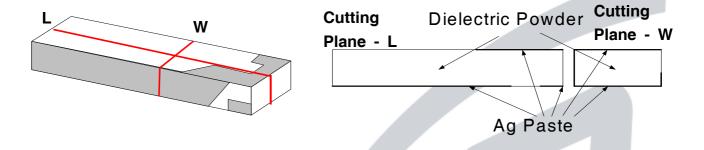
#### 13.2 Struture



**Top-Side View** 

**Bottom-Side View** 

#### 13.3 Internal cross section



#### 13.4 Material

ITEM	Material	Maker	Printing pattern SPEC
Dielectric Block	Powder	Samboo	
PATTERN	Ag Paste	Micro-M	Thickness: TYP 10//m
PAD	Ag paste	Micro-M	Thickness: Min 10/m (TYP 16~20/m)

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## 14. Attention

#### 14.1 Temperature Condition

	Range of Temperature	Unit
Application temperature	-40 ∼ +85	°C
Keeping temperature	-40 ∼ +85	°C

## 14.2 Temperature Test Condition

	Condition	Range of Temperature
Application temperature	Low	24hr normal action at -75°C
	High	24hr normal action at +150°C
Keeping temperature	Low	normal action when left for 1000hr at -75℃
	High	normal action when left for 1000hr at +85℃

 $<sup>^{\</sup>star}$  Because of the keeping temperature problem, no admission when left over +85  $^{\circ}\mathrm{C}$ 



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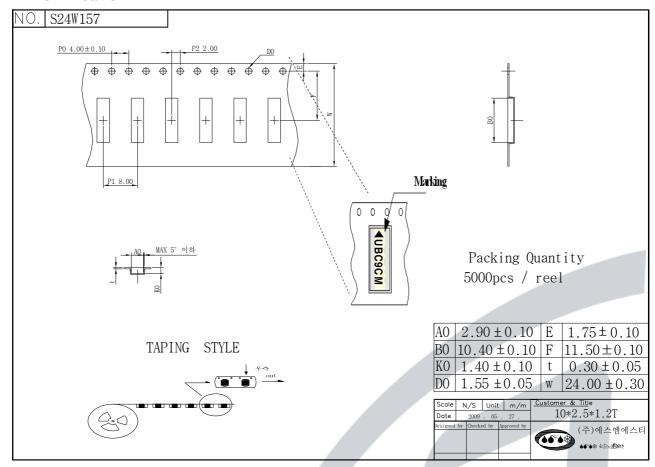


#### 15. Packing

## 15.1 Carrier/Reel

ITEM	Material	Surface Resistance	electrostatic emission	Packing method
Carrier tape	A-PET	Typical 10 <sup>8</sup> Ω	10V MAX	Heat
Cover tape	PET	Typical 10 <sup>8</sup> Ω	30V MAX	press
Reel	PS	Typical 10 <sup>8</sup> Ω	30V MAX	-

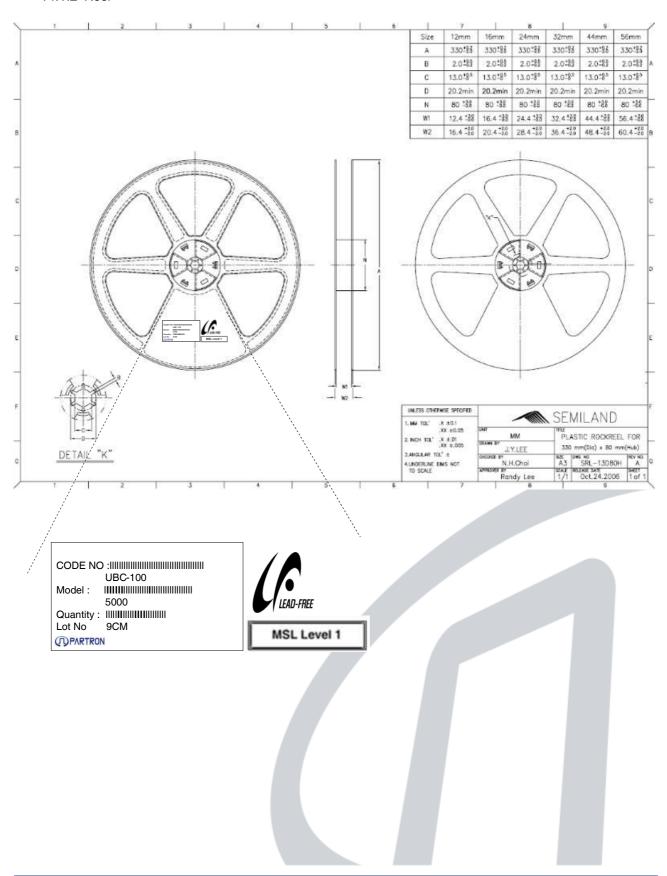
#### 15.1.1 Carrier



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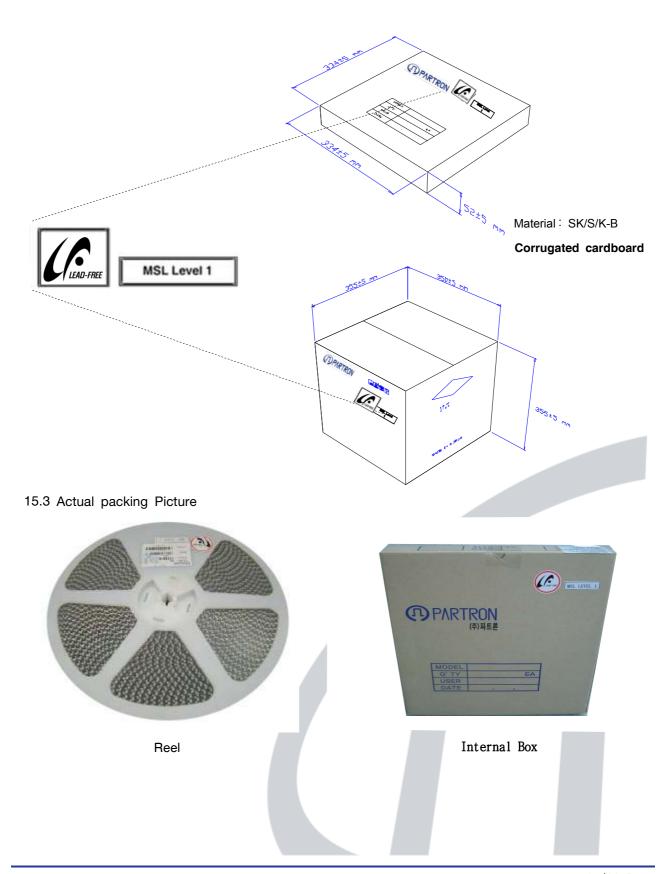
14.1.2 Reel



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15.2 Box



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External Box

CODE NO :

MODEL:

ACS2450JBAUBC

QUANTITY: 5000

DATE: 9CM

MSL LEVEL 1

Reel / Internal Box label

FROM
PARTRON,CO.LTD
SEKWOO,DONG 22-6
HWASEONG - SI
GYEONGGI - DO
445-170.KOREA



CODE NO : MODEL :

MODEL : ACS2450JBAUBC



QUANTITY: 30000



DATE: 2009 / 12 / 22

LOT NO : 9CM

CHIP ANT Partron

External Box label





## 16. Process Control

	Product		Iss	ued/Revisio	n						By designed	By chec	ked By	approved
СН	IP ANTE	NNA	Issued Revised	04.04. 05.04.		Process Control				PRCP-C00	1			
Input	FLOW	CHART	Process		Manag	ement of Facto	ors			M	anagement of qua	lity		
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
Ceramic POWDER		$\Diamond$	Import Inspection						shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/L0T	C/sheet	Return
POWDER lubricant			powder	Mixer					mixing	POWDER lubricant	Scale	PER MIXING	_	Exhaust
			Shaping	Press	pressure Mold Condition	refer to Guide Sheet	Per LOT 1/day	parameter C/SHEET	dimension weight density aspect	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust
			Plasticity	Plasticity Hole	SETTER Outside Temperature PROFILE	refer to Guide Sheet	all 2/day 1/month	C/sheet						
		$\Diamond$	Block						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/L0T 20ea/L0T all	C/sheet	Exhaust
AG PASTE			SIDE1 PAD Printing	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	_	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition  Printed  condition  breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework

Ver 1.0 (2009.12.22)



	Produc	t	Is	sued/Revisior	า	D 0 1 1				Record	By designed	By chec	ked By	approved
CHI	CHIP ANTENNA Issued 04.04.06 Revised 05.04.03  Process Control					PRCP-C0	001							
Input	FLOW	CHART	Process		Mana	agement of Factor	S			N	Management of qua	lity		
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
AG PASTE			SIDE 2 PAD Printing	Printer screen	Squeeze velocity/pres SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperatu Belt spec	0.11.01.1	1/week	Parameter	Dry Condition  Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temperatu Belt spee		1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
AG PASTE			TOP printing	Printer screen	Squeeze velocity/pres SNAP	refer to Guide Sheet	1/day	_	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperatu Belt spee	0.11.01.1	1/week	Parameter	Dry Condition  Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
AG PASTE			BOTTOM PAD Printing CTQ	printer screen	Squeeze velocity/pres SNAP	ure refer to Guide Sheet	1/day	-	PATTERN dimension aspect	refer to Guide Sheet	measure Microscope	10ea/3Jig	c/sheet	Rework

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	Product Issued/Revision				Record	E	By designed	By chec	ked By	approved						
CHIP ANTENNA			Issued Revise			Process Control			PRCP-C0	01						
Input	FLOW	CHART	Process		N	Manager	ment of Facto	rs			1	Manage	ment of qua	lity		
Materials	prepar ation	Main Process	name	Equipment Name	Chec	ked	Condition	Cycle of management	Record	Checked Item	Margin		thod of spection	Cycle of management	Record	Action
			Dry	Dryer Dry Jig	Temper Belt		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visua	l Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temper Belt		refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visua	I Inspection	all	Lot card	Exhaust Rework
		$\Diamond$	aspect inspection							aspect	Reference SPL refer to Guide Sheet		I Inspection croscope	all	Lot card production diary	Exhaust repair
			MARKING	Marking Machine						marking	Reference SPL	Visua	I Inspection	all	Lot card production diary	Rework Exhaust
		$\Diamond$	Electrical Characteristic	NETWORK Inspection Jig	proofr Condi		refer to Guide Sheet	1/2hour	C/sheet	Electrical Characteristic	refer to Guide Sheet	N	letwork	all	Lot card production diary	Exhaust repair
		$\Diamond$	aspect inspection							aspect dimension	Reference SPL refer to Guide Sheet		I Inspection croscope	all	Lot card production diary	Exhaust repair
Carrier cover reel			Taping							Quantity Direction aspect	refer to Guide Sheet	1	Manual	all	Lot card production diary	Rework
		$\Diamond$	shipper inspection	NETWORK Inspection Jig	proofr Condi		refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	mic	letwork croscope I Inspection	refer to Guide Sheet	Result Paper	return Exhaust
packing box label			packing	bar code printer						packing P/N Quantity	refer to Guide Sheet	Visua	I Inspection	all	_	Rework
		$\Diamond$	packing inspection							packing P/N Quantity	refer to Guide Sheet	Visua	I Inspection	all	-	return

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#### 17. RoHS Data

#### 1) Ceramic Powder

Parts Name	Powder(MMS-08)
Tester Organization	SGS Testing KOREA co. Ltd.
Measurement Tester	Please see the 'method' in the test report
Measurement Data	Please see the report under the table







Test Report No.: CE/2009/25184 Date: 2009/02/256 Page: 2 of 4
FUJI TITANIUM INDUSTRY CO., LTD.
12-8, SENDEN-CHO, HIRATSUKA-CITY, KANAGAWA-PREF, JAPAN

Fest results by chemical method (Unit: mg/kg)

Test Item (s):	Method	Result	MDL
rest item (s):	(Refer to)	No.1	MDL
Cadmium (Cd)	(1)	n.d.	2
Lead (Pb)	(2)	n.d.	2
Mercury (Hg)	(3)	n.d.	2
Hexavalent Chromium Cr(VI) by alkaline extraction	(4)	n.d.	2

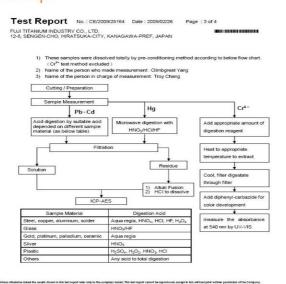
TEST PART DESCRIPTION:

Note: 1. mg/kg = ppm; 0.1wt% = 1000ppr 2. n.d. = Not Detected 3. MDL = Method Detection Limit



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Test Report No.: CE/2009/25164 Date: 2009/02/26 Page: 4 of 4
FUJI TITANIUM INDUSTRY CO, LTD.
128, SENGENCHOH, HIRATSUKA-CITY, KANAGAWA-PREF, JAPAN



\*\* End of Report \*\*

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#### 2) Ag Paste

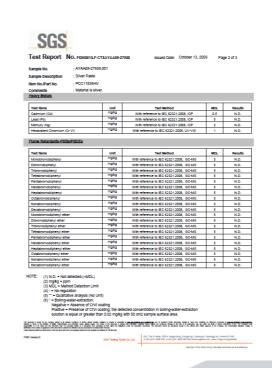
Parts Name	Silver Paste				
Tester Organization	SGS Testing KOREA co. Ltd.				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				











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#### 3) Marking Ink

Parts Name	Black Ink				
Tester Organization	Intertek Testing KOREA co. Ltd.				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				



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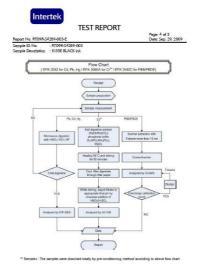
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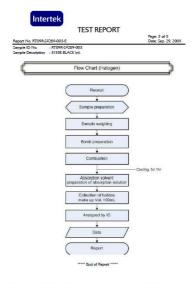
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